

#### 30V N-Channel MOSFET

### **General Description**

The 04N03 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The 04N03L meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

### **Product Summary**

BVDSS	RDSON	ID
30V	4.1mΩ	80A

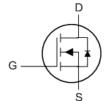
### **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

### TO-252/251 Pin Configuration







### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current 1	80	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current 1	55	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	180	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	190	mJ
I <sub>AS</sub>	Avalanche Current	48	А
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation	70	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range	-55 to 175	°C

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>		62	°C/W
R <sub>0</sub> JC	Thermal Resistance Junction -Case <sup>1</sup>		2.8	°C/W

# CMD04N03 / CMU04N03



### **30V N-Channel MOSFET**

# Electrical Characteristics (T<sub>J</sub>=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =40A		3.5	4.1	· mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A		5.1	6.4	
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1		3	V
L	Drain-Source Leakage Current	$V_{DS}$ =24V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}\mathrm{C}$			1	- uA
I <sub>DSS</sub>		$V_{DS}$ =24V , $V_{GS}$ =0V , $T_J$ =125 $^{\circ}\mathrm{C}$			100	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =25A		22		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.5		Ω
Qg	Total Gate Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =40A		24		
Q <sub>gs</sub>	Gate-Source Charge			10		nC
$Q_gd$	Gate-Drain Charge			7.2		
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		9		
Tr	Rise Time			22		no
T <sub>d(off)</sub>	Turn-Off Delay Time			28		ns
T <sub>f</sub>	Fall Time			18		
C <sub>iss</sub>	Input Capacitance			3500		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		650		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			300		

# **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			80	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2</sup>	7 VG-VD-OV , FOICE CUITEIN			180	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =40 A , T <sub>J</sub> =25℃			1.2	V

#### Note:

1. The data tested by surface mounted on a 1 inch $^2\,\text{FR-4}$  board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{DD}$  =25V,  $V_{GS}$  =10V,L=0.1mH,  $I_{AS}$  =40A

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